

**General Description**

The DSC613PI3A-0105 is a three-output low power MEMS clock generator.

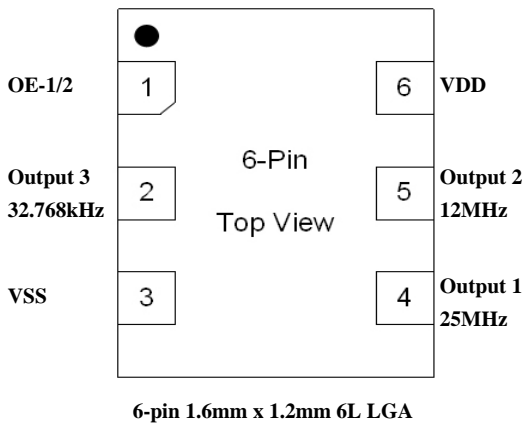
The MEMS based clock generator eliminates the need of external crystal or reference clock.

Refer to [DSC613 master data sheet](#) to read full descriptions.

**Features**

- Three LVC MOS clock outputs: 25MHz, 12MHz, 32.768kHz
- Ultra-small package size: 1.6mm x 1.2mm 6L LGA
- High stability:  $\pm 20$ ppm
- Temperature range:  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$
- Low power consumption:  $\sim 5.2\text{mA}$  (all outputs active)
- Wide supply voltage range: 1.71V -3.63V VDD
- Excellent shock and vibration immunity
- High reliability
- Lead free and RoHS compliant
- AEC-Q100 automotive grade available

**Pin Configuration and Description**



Pin Number	Pin Name	Pin Type	Pin Description
1	OE-1/2	I	Output Enable H = Output Active L = Output Disabled (High Impedance)
2	Output 3	O	32.768kHz LVC MOS Clock Output
3	VSS	Power	Power Supply Ground
4	Output 1	O	25MHz LVC MOS Clock Output Controlled by Pin 1 (OE-1/2)
5	Output 2	O	12MHz LVC MOS Clock Output Controlled by Pin 1 (OE-1/2)
6	VDD	Power	Power Supply

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## Ordering Information

Ordering Part Number	Temperature Range	High Stability	Shipping	Package
DSC613PI3A-0105	-40°C to +85°C	±20ppm	Bag	1.6mm x 1.2mm 6L LGA
DSC613PI3A-0105T	-40°C to +85°C	±20ppm	Tape and Reel	1.6mm x 1.2mm 6L LGA

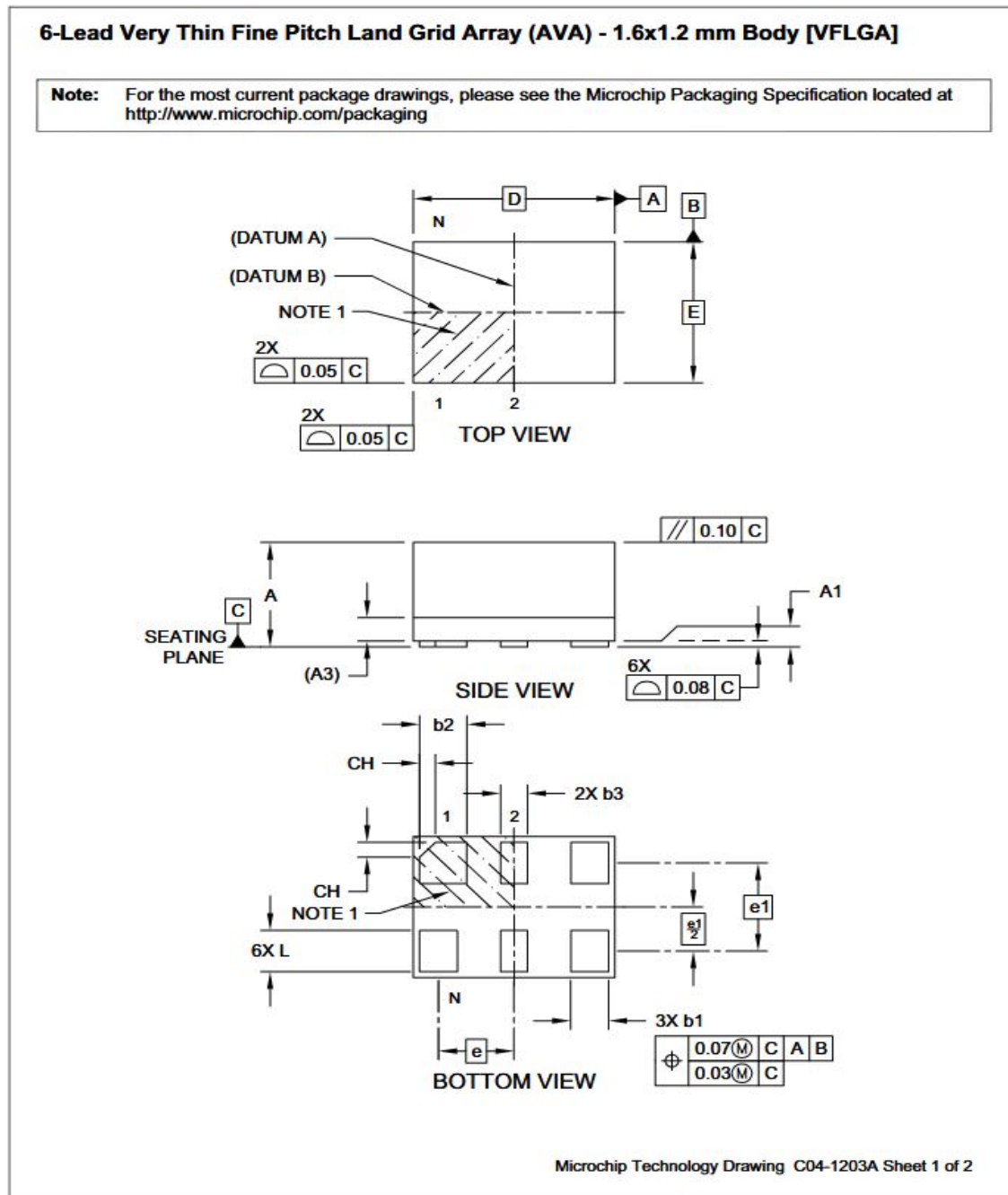
Devices are Green and RoHS compliant. Sample material may have only a partial top mark.

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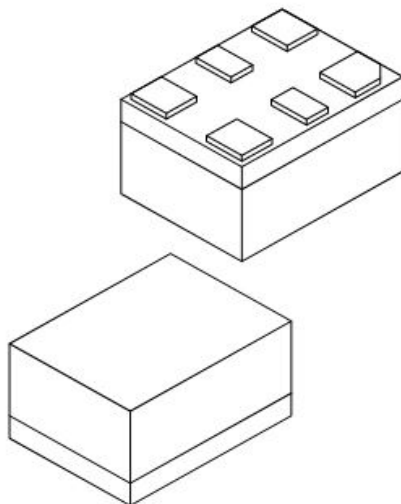
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**6-Lead 1.6 mm x 1.2 mm VFLGA Package Outline and Recommended Land Pattern**



**6-Lead Very Thin Fine Pitch Land Grid Array (AVA) - 1.6x1.2 mm Body [VFLGA]**

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	6		
Terminal Pitch	e	0.60 BSC		
Terminal Pitch	e1	0.75 BSC		
Overall Height	A	0.79	0.84	0.89
Standoff	A1	0.00	0.02	0.05
Substrate Thickness (with Terminals)	A3	0.20 REF		
Overall Length	D	1.60 BSC		
Overall Width	E	1.20 BSC		
Terminal Width	b1	0.25	0.30	0.35
Terminal Width	b2	0.325	0.375	0.425
Terminal Width	b3	0.20	0.25	0.30
Terminal Length	L	0.30	0.35	0.40
Terminal 1 Index Chamfer	CH	-	0.125	-

**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M

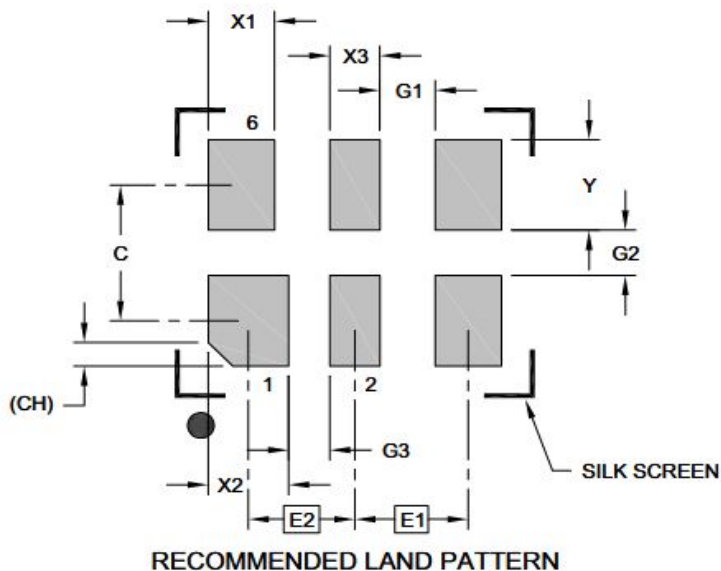
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

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**6-Lead Very Thin Fine Pitch Land Grid Array (AVA) - 1.6x1.2 mm Body [VFLGA]**

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch (X3)	E1		0.60 BSC	
Contact Pitch	E2		0.56 BSC	
Contact Spacing	C		0.75	
Contact Width (X3)	X1			0.35
Contact Width	X2			0.43
Contact Width (X2)	X3			0.27
Contact Pad Length (X6)	Y			0.50
Space Between Contacts (X4)	G1	0.29		
Space Between Contacts (X3)	G2	0.25		
Space Between Contacts	G3	0.22		
Contact 1 Index Chamfer	CH	0.13 X 45° REF		

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-3203A